

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
30 January 2003 (30.01.2003)

PCT

(10) International Publication Number
WO 03/009317 A2

(51) International Patent Classification⁷: **H01G**

(21) International Application Number: PCT/IT02/00465

(22) International Filing Date: 16 July 2002 (16.07.2002)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
MI2001A001557 20 July 2001 (20.07.2001) IT
MI2002A000689 3 April 2002 (03.04.2002) IT

(71) Applicant: **SAES GETTERS S.P.A.** [IT/IT]; Viale Italia,
77, I-20020 Lainate (IT).

(72) Inventor: **AMIOTTI, Marco**; Via Ludovico il Moro, 2,
I-27029 Vigevano (IT).

(74) Agents: **ADORNO, Silvano**; Società Italiana Brevetti
S.p.A., Via Carducci, 8, I-20123 Milano_ et al. (IT).

(81) Designated States (*national*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VN, YU, ZA, ZM, ZW.

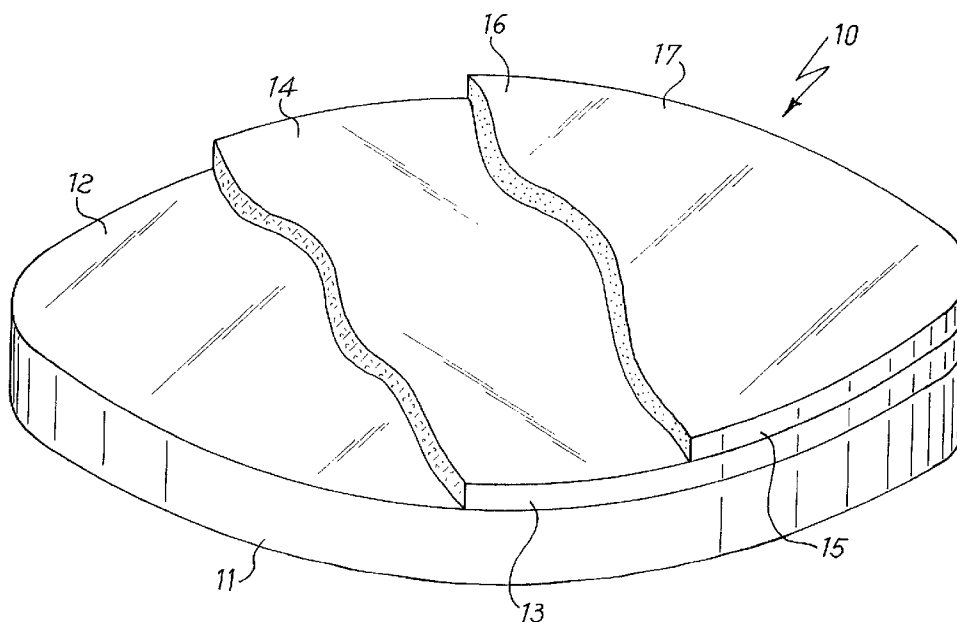
(84) Designated States (*regional*): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— without international search report and to be republished upon receipt of that report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: SUPPORT WITH INTEGRATED DEPOSIT OF GAS ABSORBING MATERIAL FOR MANUFACTURING MICROELECTRONIC, MICROOPTOELECTRONIC OR MICROMECHANICAL DEVICES



(57) Abstract: It is described in different embodiments thereof a support (10; 20) for manufacturing microelectronic, microoptoelectronic or micromechanical devices requiring gas absorption for their correct operation, comprising a mechanical supporting base (11; 21), a layer (13) of a gas absorbing material on the base and a layer for temporary protection of the gas absorbing material, that is removed during the manufacture of the devices.



WO 03/009317 A2